

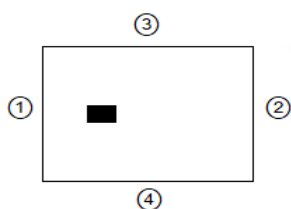
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

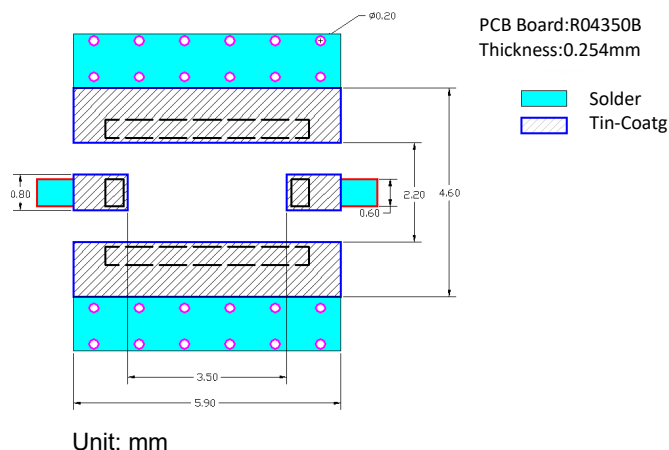
No.	Parameter	SPEC
1	Frequency (MHz)	2200~3800MHz
2	Insertion Loss	≤2.5dB
3	VSWR	≤1.5
4	Ripple	≤1.0dB
5	Attenuation	≥40dB@10~1600MHz ≥40dB@4500~8000MHz
6	Power	2W
7	In/Output Impedance	50 Ω
8	Operation Temperature Range	-40°C~+70°C
9	Storage Temperature Range	-55°C~+85°C

Construction

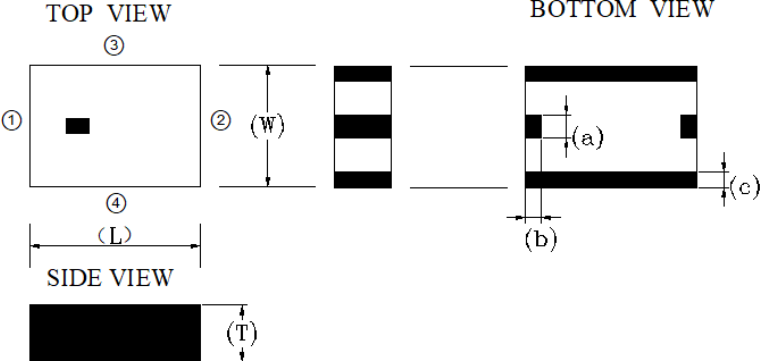


PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

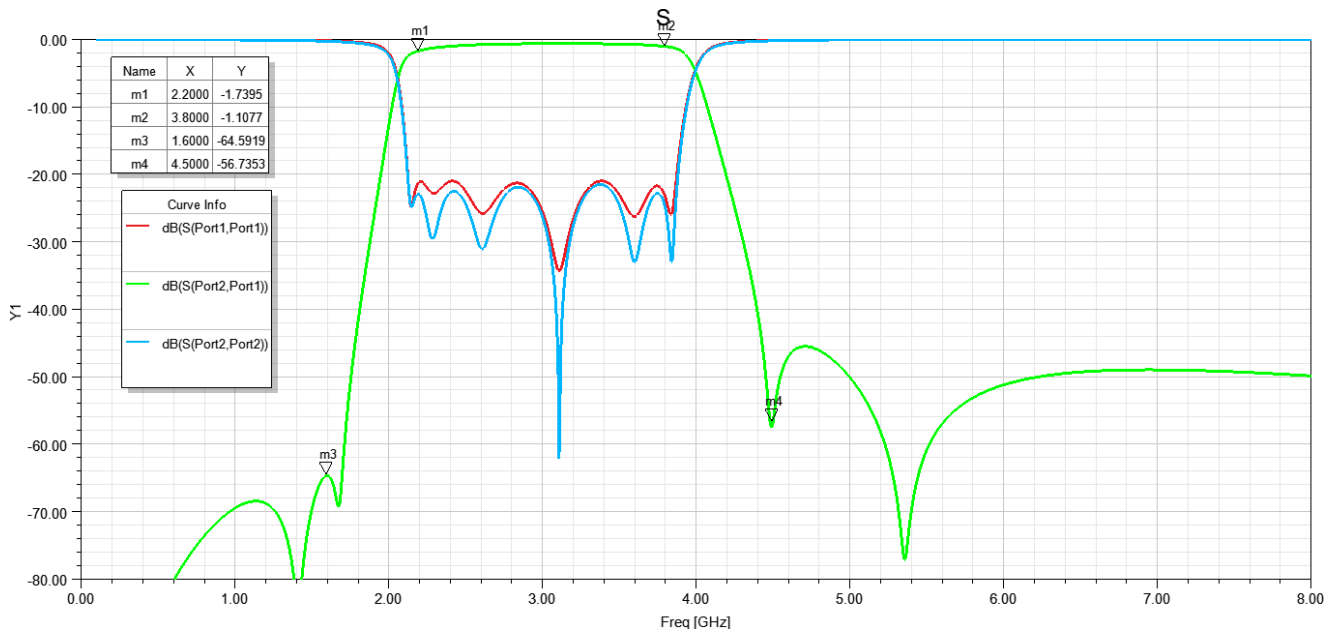
Mounting Considerations



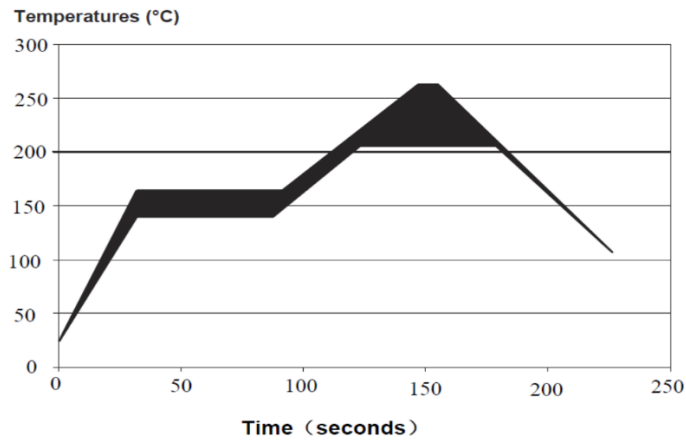
Dimensions

Figure	Symbol	Dimension (mm)
	L	4.50±0.15
	W	3.20±0.15
	T	1.50±0.15
	a	0.60±0.10
	b	0.40±0.05
	c	0.40±0.05

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.